

FORM PTO-1449  
(Rev. 7-80)U.S. Department of Commerce  
Patent and Trademark OfficeAttorney Docket No.  
TESSERA 3.0-102 II DIV

Serial No.

LIST OF PRIOR ART CITED BY APPLICANT  
(Use several sheets if necessary)Applicant  
Thomas H. DiStefanoFiling Date  
HEREWITH

Group

JC836 U.S. PTO  
09/16/99

07/27/00

## U.S. PATENT DOCUMENTS

*EXAMINER INITIALS		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<u>A</u>	AA	5,834,339	11/10/98	DiStefano et al.	438	125	
	AB	5,347,159	9/13/94	Khandros et al.	257	692	
	AC	5,557,501	9/17/96	DiStefano et al.	361	704	
	AD	5,124,277	6/92	Tsumura	437	9	
	AE	4,948,221	8/90	Yates	358	96.20	
	AF	5,473,512	12/95	Degani et al.	361	760	
	AG	5,216,278	6/93	Lin et al.	257	688	
	AH	5,717,252	2/98	Nakashima et al.	257	707	
	AI	5,214,307	5/93	Davis	257	676	
	AJ	5,239,198	8/93	Lin et al.	257	693	
<u>G</u>	AK	5,428,889	7/95	Mita et al.	29	827	

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
<u>G</u>	AL	WO 92/05582	4/2/92	WIPO				
	AM							
	AN							
	AO							
	AP							

## OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)

<u>22</u>	AR		Design for Minimum Chip Joint Stress, IBM Technical Disclosure Bulletin, Vol. 32, No. 7, December 1989, pp. 12-13.					
<u>22</u>	AS		Multichip Module Technologies and Alternatives: The Basics, Doane and Franzon, Eds. 1993, pp. 429-430 and 569-613.					
<u>22</u>	AT		Metallurgy For Engineers, E. C. Rollason, Fourth Edition, 1973, pp. 218-220.					

EXAMINER

JMD

DATE CONSIDERED

8-27-01

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.

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## U.S. PATENT DOCUMENTS

*EXAMINER INITIALS		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
G	AA	4,862,322	8/89	Bickford et al.	361	386	
G	AB	5,866,949	2/99	Schueller	257	778	
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

## FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AM							
	AN							
	AO							
	AP							

## OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)

G	AR		Materials Handbook, Brady et al., Thirteenth Edition, 1991, pp. 487-488.					
G	AS		Multichip Module-Technologies and Alternatives - The Basics: Doane and Franzon, eds. pp. 56-69 DATE NOT AVAILABLE					
	AT							

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GMO

DATE CONSIDERED

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